



MOSFETs Silicon 500V N-Channel MOS

■ Applications

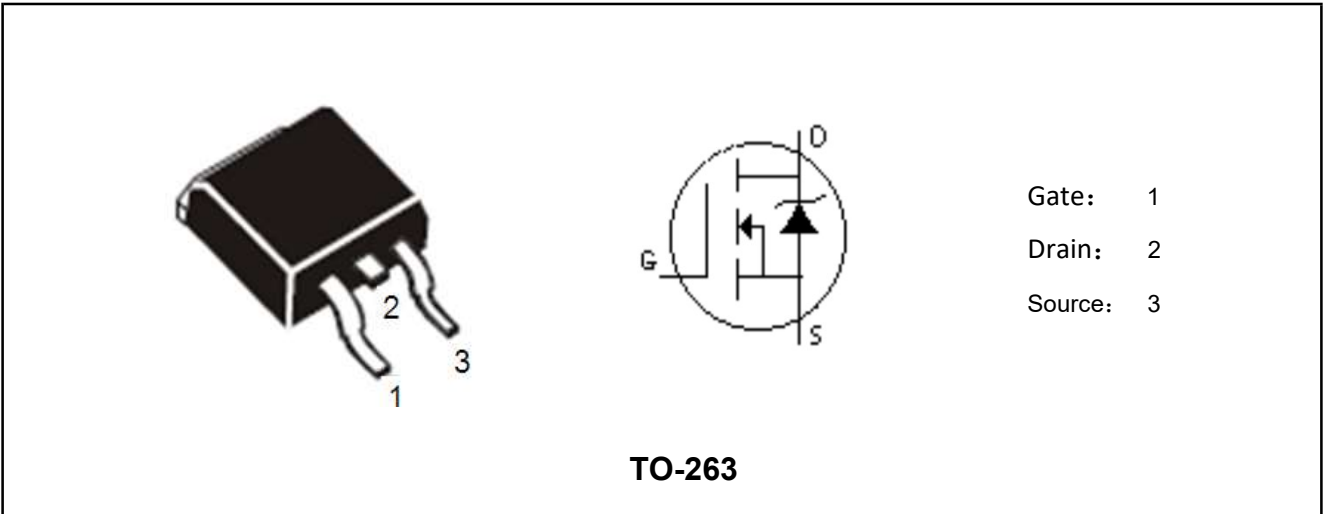
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

■ Features

- Multi-Epi process SJ-FET
- Low  $R_{DS(ON)}$
- Ultra Low Gate Charge
- RoHS and Halogen-Free Compliant
- 100% UIS and RG Tested

■ Product Summary

$V_{DS} @ T_{j,max}$	550	V
$I_D$	24	A
$R_{DS(ON),Typ}@10V$	0.12	$\Omega$
$Q_g$	28	nC



Marking	Package	Packaging	Min. package quantity
ML140R50C	TO-263	Tube	1000
		Tape & Reel	800





### ■ Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	500	V
Gate-Source Voltage	$V_{GS}$	±30	V
Continuous Drain Current Tc=25°C (Note 1)	$I_D$	24	A
Continuous Drain Current Tc=100°C (Note 1)		15	
Drain Current-Pulsed (Note 1)	$I_{DM}$	70	A
Total Dissipation	$P_D$	150	W
Junction Temperature	$T_j$	150	°C
Storage Temperature	$T_{stg}$	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	485	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

### ■ Thermal Characteristics

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	$R_{\theta JC}$	0.83	°C/W
Maximum Junction-to-Ambient (Note 3)	$R_{\theta JA}$	60	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}=50V$ ,  $T_{ch}=25^\circ C$ (initial),  $I_{AS}=24A$ ,  $R_g=25\Omega$ .

Note 3: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ . The value in any given application depends on the user's specific board design.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





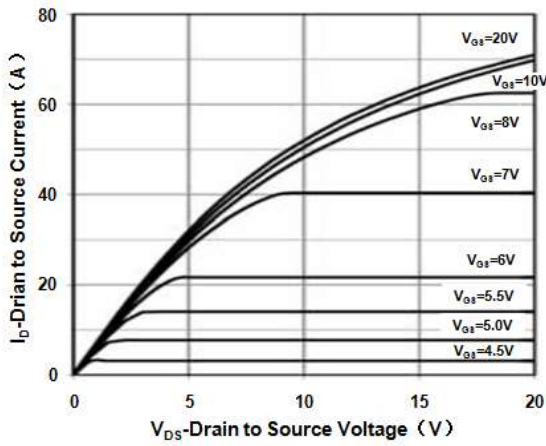
### ■ Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	500	-	-	V
		T <sub>J</sub> =150°C	550	-	-	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.5	3.5	4.5	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =12A	-	0.12	0.14	Ω
		T <sub>J</sub> =150°C	-	0.3	-	
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	1330	-	pF
Output Capacitance	C <sub>oss</sub>		-	540	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	12	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	4.8	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =12A, V <sub>GS</sub> =10V, R <sub>G</sub> =20Ω	-	15	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	10	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	110	-	ns
Turn-Off Rise Time	t <sub>f</sub>		-	9	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =12A, V <sub>GS</sub> =10V	-	28	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	8.6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	8.8	-	nC
<b>Source-Drain Characteristics</b>						
Max. Diode Forward Current	I <sub>S</sub>		-	-	24	A
Max. Pulsed Forward Current	I <sub>SM</sub>		-	-	70	A
Diode Forward Voltage	V <sub>sd</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =12A	-	0.9	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =400V, I <sub>F</sub> =12A, di/dt=100A/us	-	330	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	4.43	-	μC

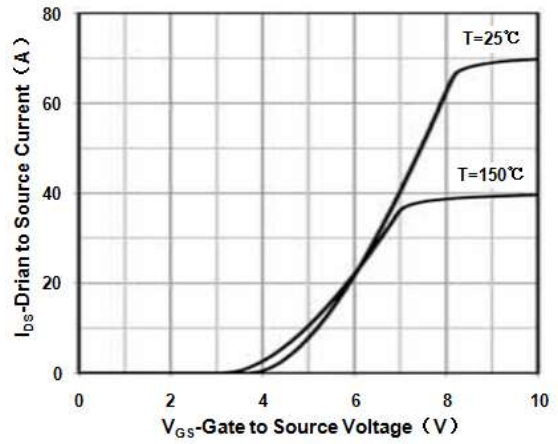




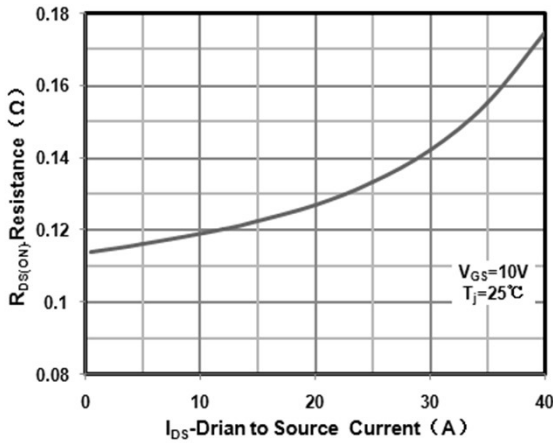
### ■ Characteristics Curves



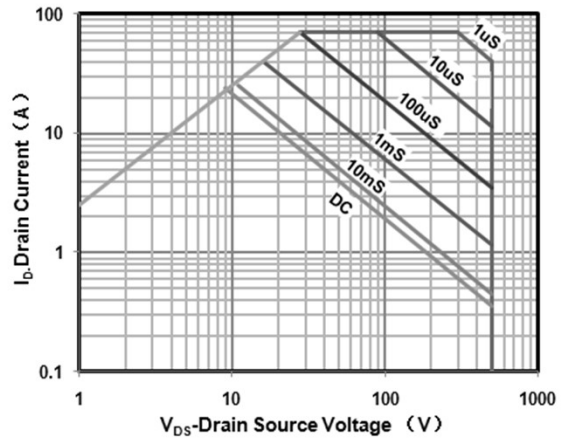
Output Characteristics



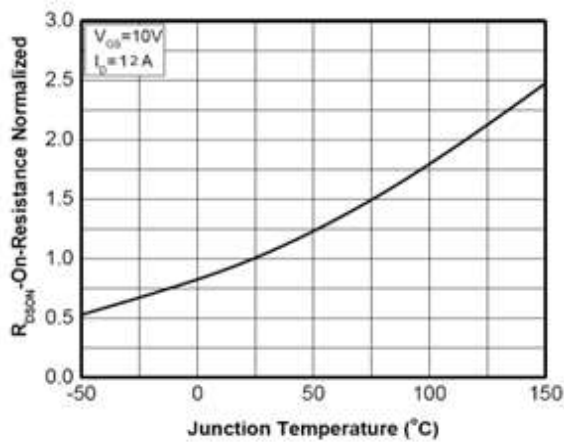
Transfer Characteristics



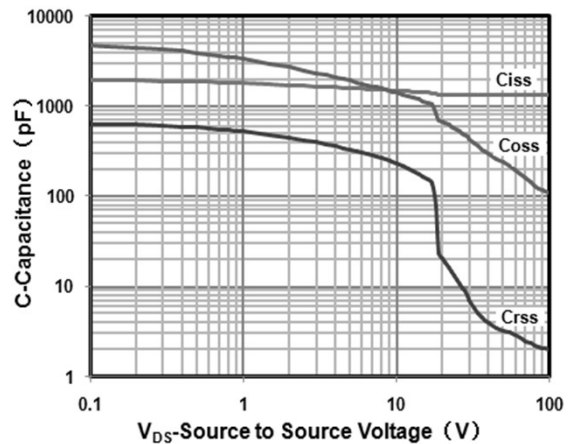
On Resistance Vs Drain Current



Maximum Safe Operating Area

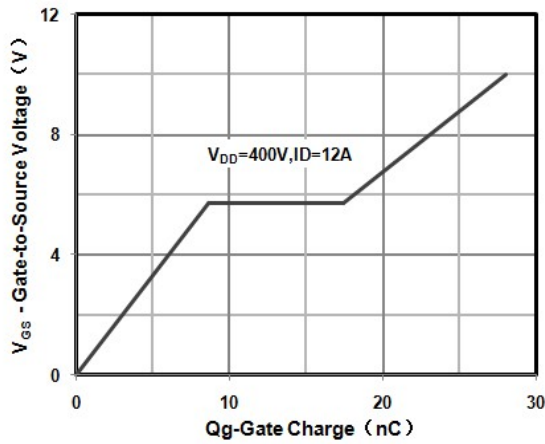


Rdson-Junction Temperature

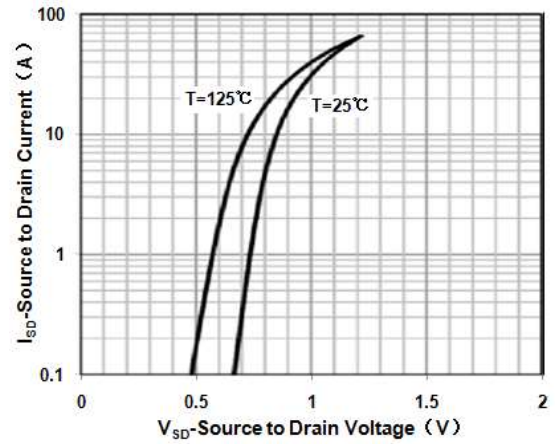


Capacitance

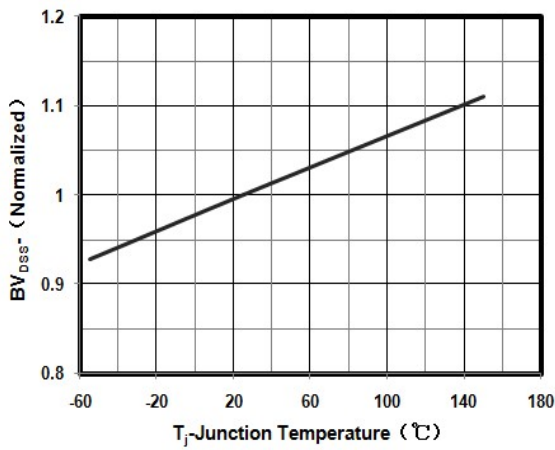




Gate Charge Waveform



Source-Drain Diode Forward Voltage



Breakdown Voltage Vs Junction Temperature

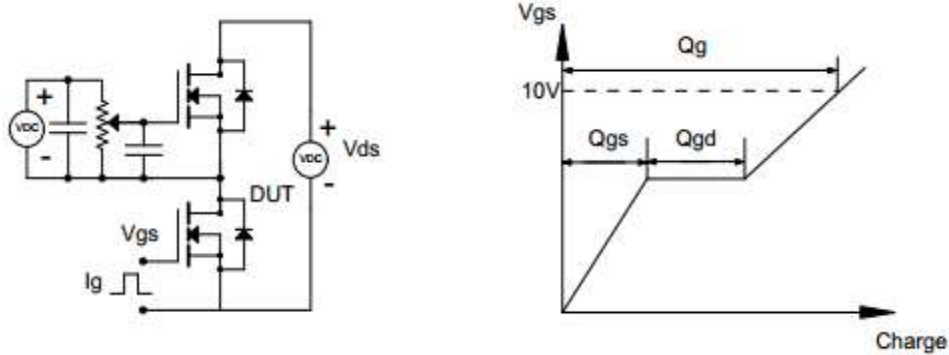
Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



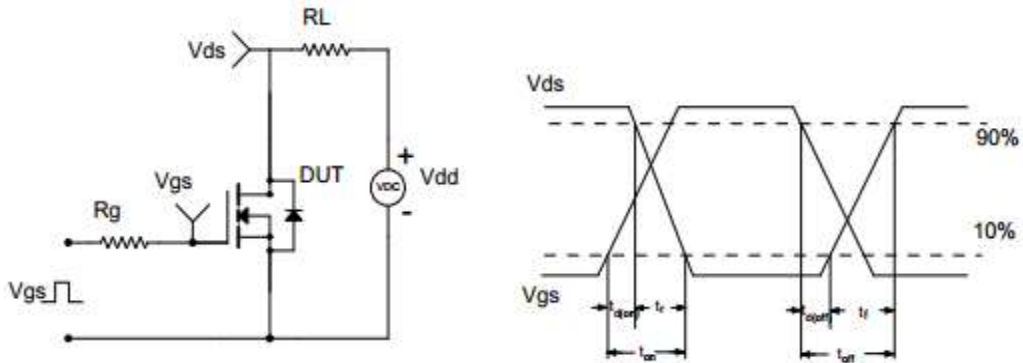


■ Test Circuit & Waveform

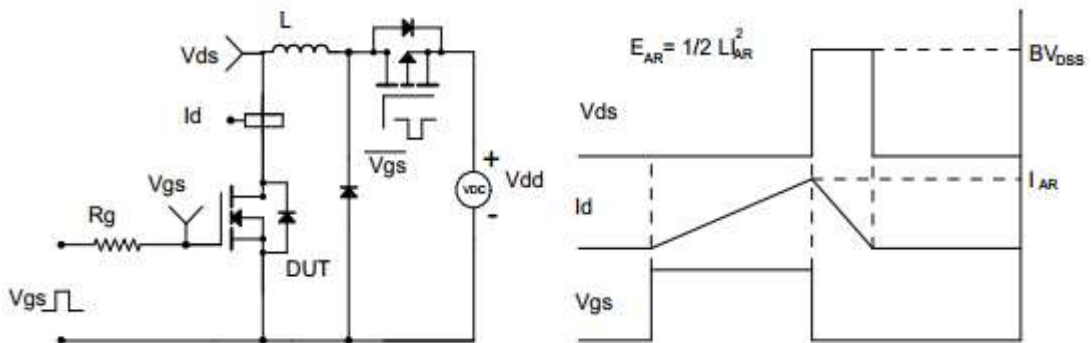
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveform





■ TO-263 Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	4.42		4.72	E	8.99		9.29
B	1.22		1.4	e1	2.44	2.54	2.64
b	0.76		0.86	e2	4.98		5.18
b1	1.22		1.4	L1	14.7	15.1	15.5
b2	0.33		0.43	L2	2	2.3	2.6
C	1.22		1.35	L3	1.5		2
D	9.95		10.25	K	-0.1		0.1

